

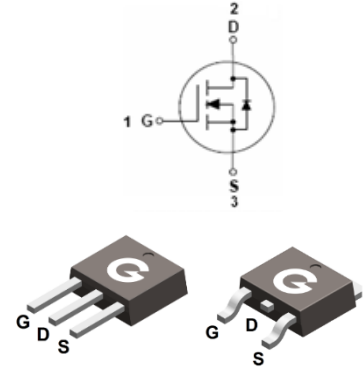
### Features

- Low  $R_{DS(ON)}$
- Fast switching
- Low gate charge
- Low Reverse transfer capacitances

**HF**

### Mechanical Data

- Case: TO-251, TO-252
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matted-Tin plated; Solderable Per MIL-STD-202, Method 208


**TO-251**
**TO-252**

### Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
BL5N50I	TO-251	80 pcs / Tube	5N50I
BL5N50D	TO-252	80pcs / Tube or 2500pcs / Tape & Reel	5N50D

### Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DSS}$	500	V
Gate-to-Source Voltage	$V_{GSS}$	$\pm 30$	V
Continuous Drain Current ( $T_C = 25^\circ\text{C}$ )	$I_D$	5	A
Continuous Drain Current ( $T_C = 100^\circ\text{C}$ )		3.1	A
Pulsed Drain Current ( $t_p = 10\mu\text{s}$ , $T_C = 25^\circ\text{C}$ )	$I_{DM}$	20	A
Single Pulse Avalanche Energy <sup>*3</sup>	$E_{AS}$	125	mJ
Power Dissipation ( $T_C = 25^\circ\text{C}$ )	$P_D$	78	W
Operating Junction Temperature Range	$T_J$	-55 ~ +150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 ~ +150	$^\circ\text{C}$

### Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	-	-	1.6	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Air <sup>*1</sup>	$R_{\theta JA}$	-	-	50	$^\circ\text{C/W}$

### Electrical Characteristics

 (@ T<sub>A</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
V <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	500	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 500V, V <sub>GS</sub> = 0V	-	-	1	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> = ±30V, V <sub>DS</sub> = 0V	-	-	±100	nA
<b>On Characteristics</b>						
R <sub>DS(ON)</sub>	Drain-Source On-resistance *2	V <sub>GS</sub> = 10V, I <sub>D</sub> = 2.5A	-	-	1.5	Ω
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	2	-	4	V
<b>Dynamic Characteristics</b>						
C <sub>ISS</sub>	Input Capacitance	V <sub>GS</sub> = 0V V <sub>DS</sub> = 25V f = 1MHz	-	584	-	pF
C <sub>OSS</sub>	Output Capacitance		-	61	-	
C <sub>RSS</sub>	Reverse Transfer Capacitance		-	4	-	
<b>Switching Characteristics</b>						
t <sub>d(ON)</sub>	Turn-on Delay Time *4	V <sub>DD</sub> = 250V I <sub>D</sub> = 5A R <sub>G</sub> = 10Ω	-	14	-	ns
t <sub>r</sub>	Turn-on Rise Time *4		-	18	-	
t <sub>d(OFF)</sub>	Turn-Off Delay Time *4		-	32	-	
t <sub>f</sub>	Turn-Off Fall Time *4		-	11	-	
Q <sub>G</sub>	Total Gate-Charge	V <sub>DD</sub> = 400V	-	12.6	-	nC
Q <sub>GS</sub>	Gate to Source Charge	V <sub>GS</sub> = 10V	-	3.1	-	
Q <sub>GD</sub>	Gate to Drain (Miller) Charge	I <sub>D</sub> = 5A	-	4.9	-	
<b>Source-Drain Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage *2	I <sub>SD</sub> = 5A, V <sub>GS</sub> = 0V	-	-	1.5	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>SD</sub> = 5A, V <sub>R</sub> = 400V	-	328	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI/dt = 100A/μs	-	1.555	-	μC

**Notes:**

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper
2. The data tested by pulsed, pulse width ≤ 300μs, duty cycle ≤ 2%
3. The E<sub>AS</sub> data shows Max. rating. The test condition is V<sub>DD</sub> = 100V, V<sub>GS</sub> = 15V, L = 10mH
4. Guaranteed by design, not subject to production

Ratings and Characteristics Curves (@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

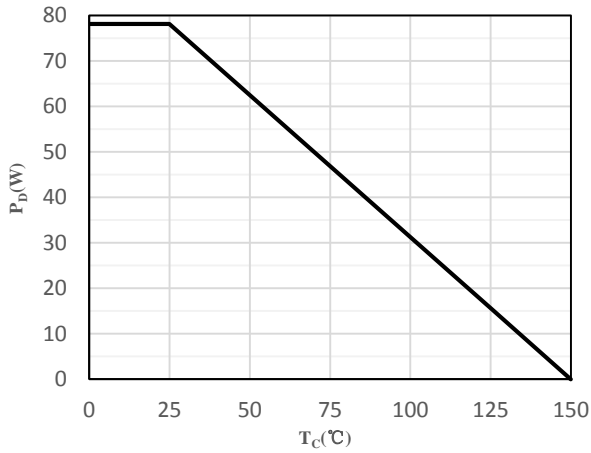


Fig 1 Power Dissipation

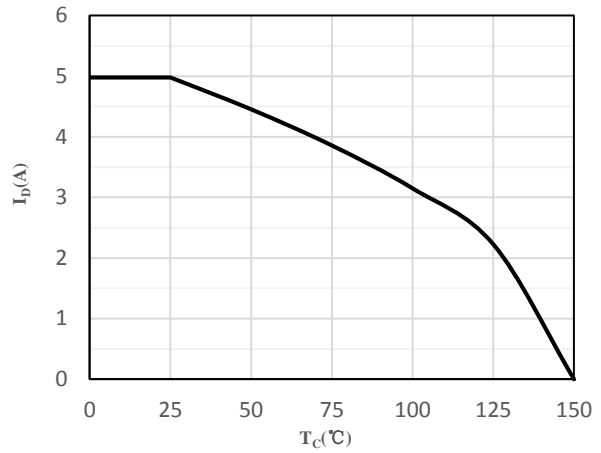


Fig 2 Drain Current

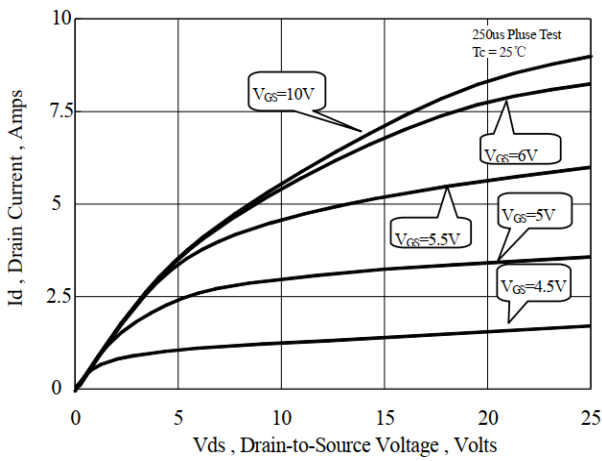


Fig 3 Typical Output Characteristics

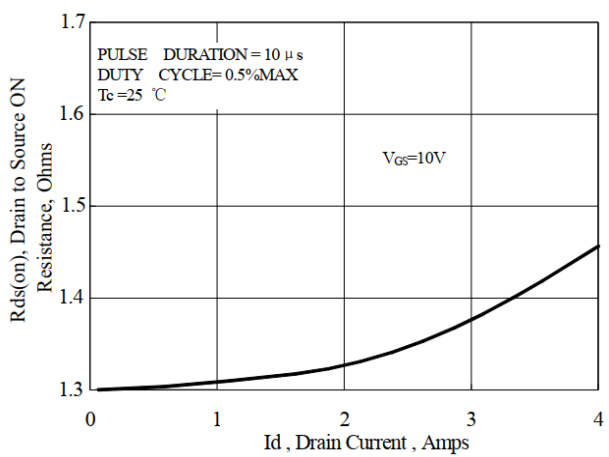


Fig 4 On-Resistance vs. Drain Current and Gate Voltage

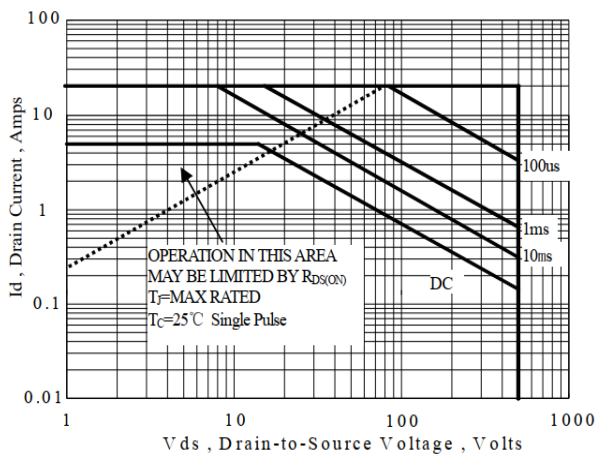


Fig 5 Safe Operation Area

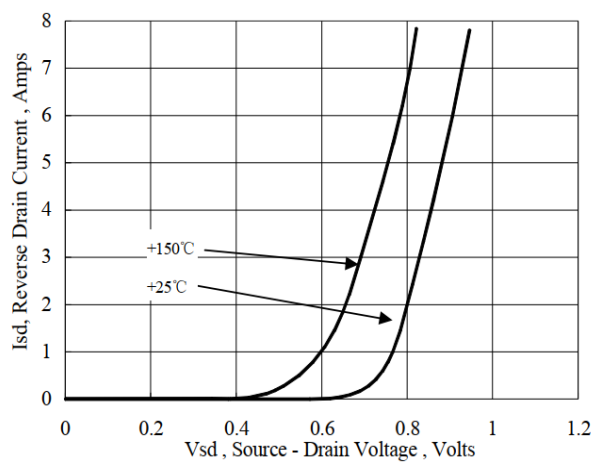
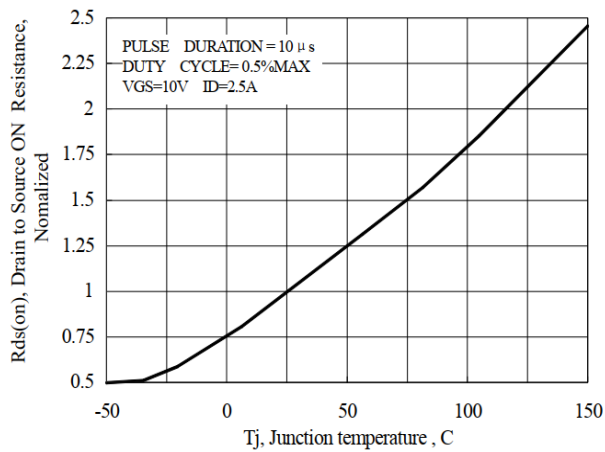
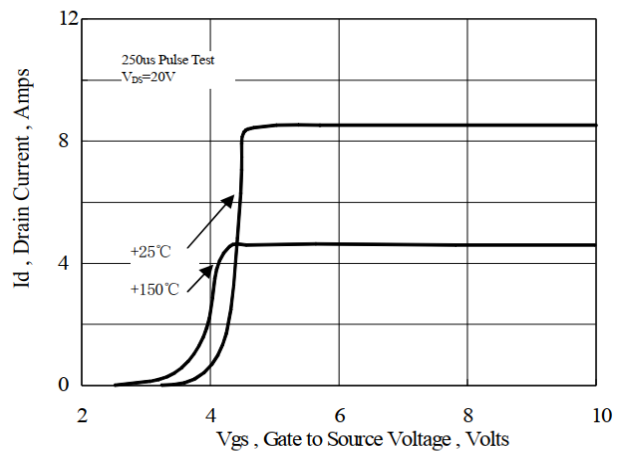


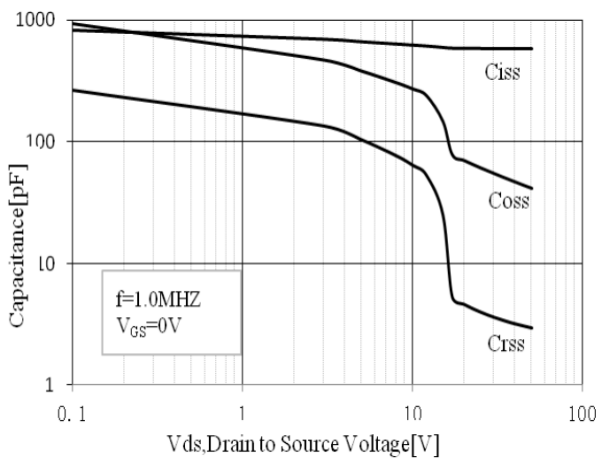
Fig 6 Body-Diode Characteristics



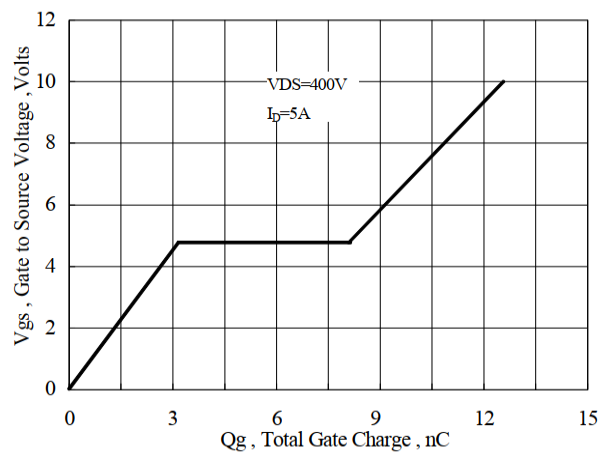
**Fig 7 Normalized On-Resistance vs. Junction Temperature**



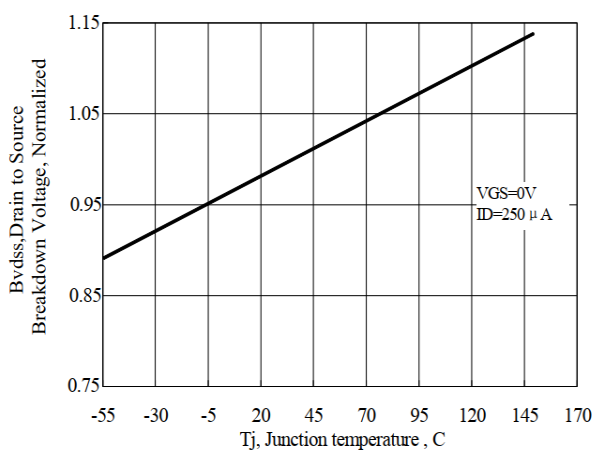
**Fig 8 Transfer Characteristics**



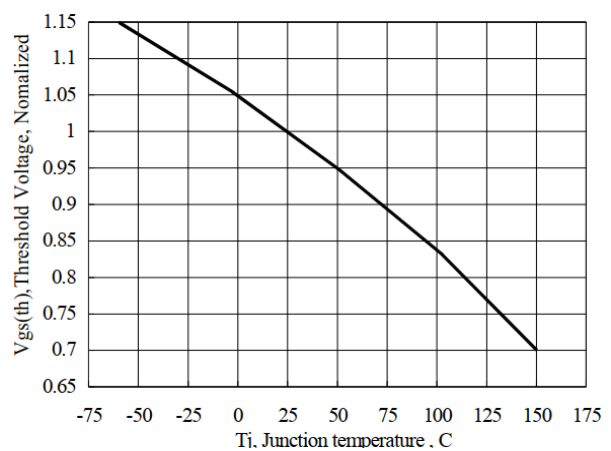
**Fig 9 Capacitance Characteristics**



**Fig 10 Gate-Charge Characteristics**

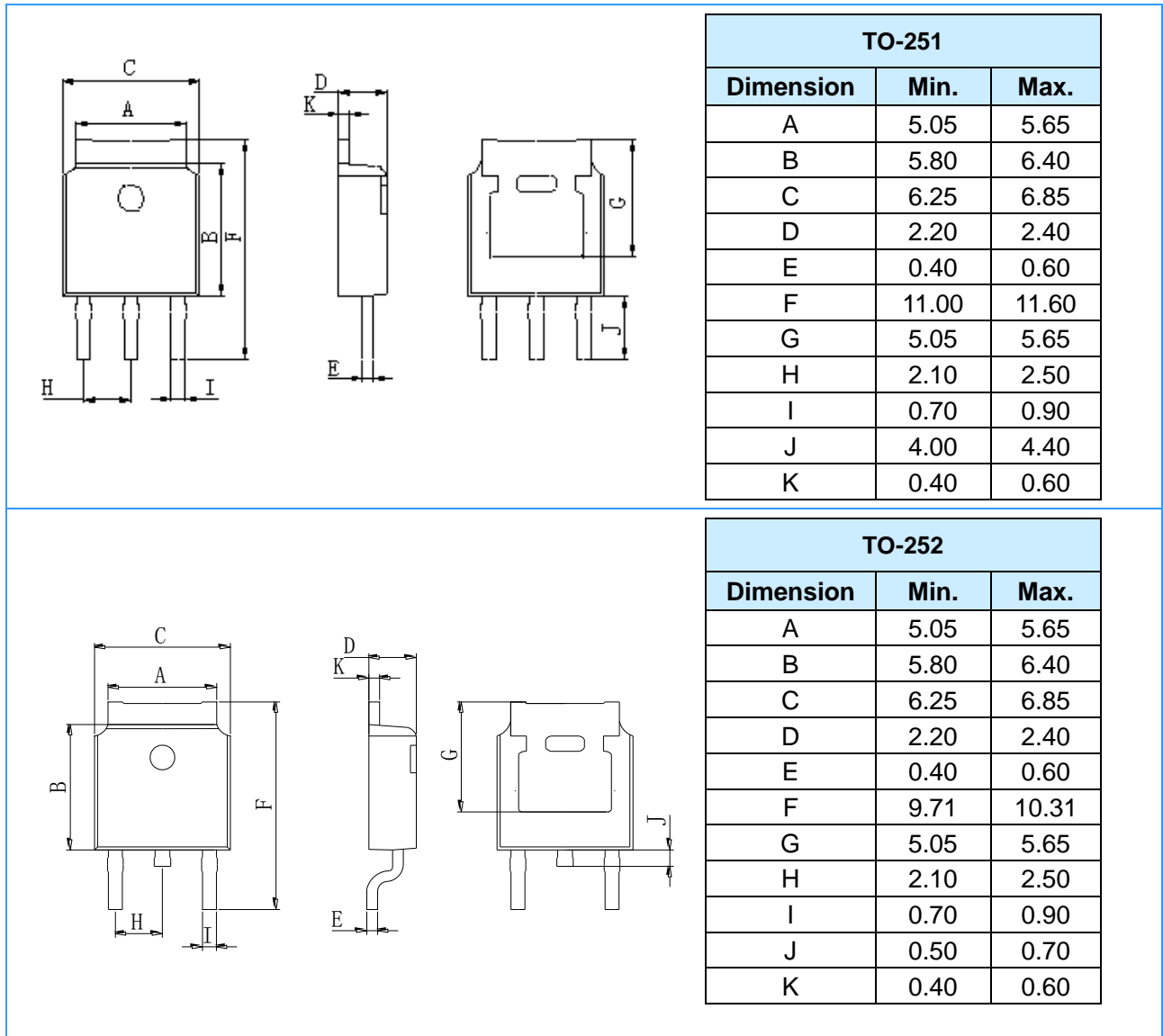


**Fig 11 Normalized Breakdown Voltage vs. Junction Temperature**

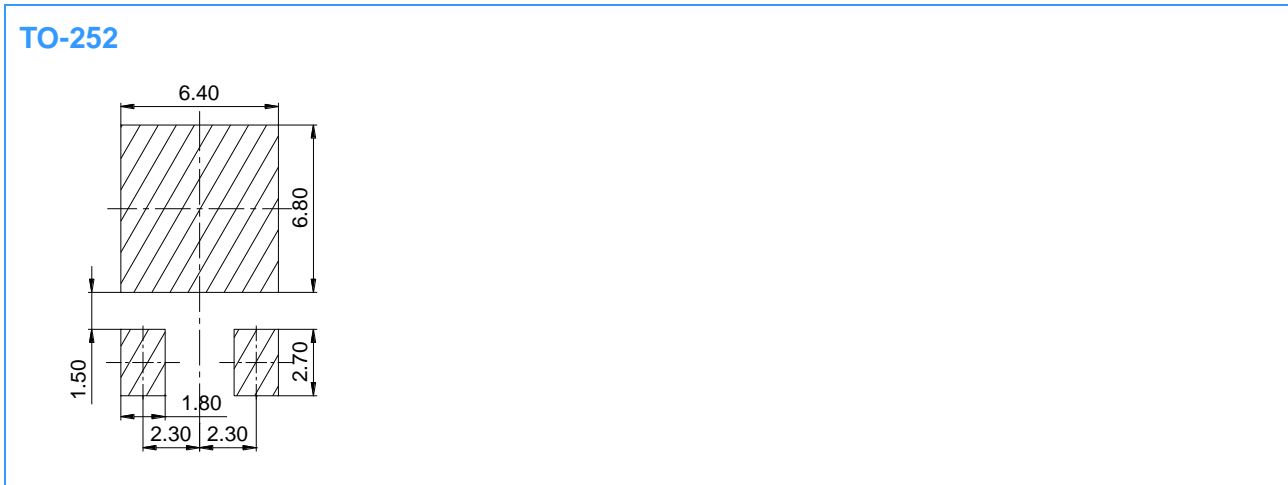


**Fig 12 Normalized  $V_{GS(th)}$  vs. Junction Temperature**

**Package Outline Dimensions** (Unit: mm)



**Mounting Pad Layout** (Unit: mm)



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